

IN THE CLAIMS

1. (Canceled)

2. (currently amended) A system for processing a semiconductor device, the system comprising:

a processing chamber heated by heating elements; and

a first plate positioned within said processing chamber and defining a first internal cavity configured to receive a first gas through a first passage into said first internal cavity at a first temperature and to emit said first gas from said first internal cavity at a second temperature through a second passage; and

a second plate disposed adjacent to said first plate, said first plate and said second plate provided between said heating elements and defining a processing area therebetween, said second plate defining a second internal cavity configured to receive a second gas through a first passage into said second internal cavity at a first temperature and to emit said second gas from said second internal cavity at a second temperature through a second passage, said first emitted gas and said second emitted gas varying the temperature of said processing area.

3. (currently amended) The system of Claim 2, wherein said second passage comprise comprises a plurality of holes defined on a surface of said first and said second plates.

4. (previously presented) The system of Claim 2, wherein said first plate and said second plate comprise a heat source for heating said plate to a preselected temperature.

5. (previously presented) The system of Claim 2, wherein said first gas is taken from the group consisting of N₂, He, H₂, O₂, Ar and gas mixtures containing He, H₂, O₂, Ar and N₂.

6. (previously presented) The system of Claim 2, wherein said internal cavity further comprises a buffer to disperse said first gas throughout said internal cavity.

7. (canceled)

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8. (currently amended) A system for wafer processing comprising:
a chamber heated by heating elements; and
a first heatable plate and a second heatable plate ~~positionable~~ positioned between said heating elements within said chamber, and defining a processing area therebetween, each of said heatable plates including:

an internal cavity defining an internal wall and configured to receive a gas;
means for heating said internal wall to a preselected temperature; and
an outlet portion defining a plurality of holes for emitting said gas to said processing area;
said gas varying the temperature of said processing area.

9. (previously presented) The system of Claim 8, wherein said gas is taken from the group consisting of He, H₂, O₂, Ar, N₂ and gas mixtures containing He, H₂, O₂, Ar, and N₂.

10. (previously presented) The system of Claim 8, wherein said internal cavity further comprises a buffer to disperse said first gas throughout said internal cavity.

11.-16. (canceled)

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